CPGA

Ceramic Pin Grid Array Package (CPGA)

Amkor Technology is committed to continuing to service this long established standard industry package. This thru-hole package consists of a co-fired ceramic base that has a matrix of pins brazed onto the bottom of the base. The lid for this package can be either ceramic "frit sealed" or metal "solder sealed". The package can be designed for either cavity up or cavity down configurations. This IC package technology allows application and design engineers to maximize the performance characteristics of semiconductors (silicon & GaAs). CPGAs are designed for low inductance, enhanced thermal operation and capability. Custom performance enhancements are available for significant improvements in electrical response demanded by advancing electronics.

Features:

The CPGA offers a variety of features. From innovative designs and expanding package offerings, Amkor provides a platform from prototype-to-production.

- Flexible pin counts
- Variety of body sizes
- 50 mil & 100 mil pin pitch
- Staggered and full pin array matrix
- Heat plate / heat slug / heat sink
- Exceptional thermal and electrical performance by design
- Multi-layer, ground / power
- Cavity Up and Cavity Down configurations available
- Cavity package

Applications:

Semiconductor technologies find enhanced performance by using the integrated design features of the CPGA package. Microprocessors / controllers, ASICs, Gate Arrays, memory, DSPs and PC chip sets find the CPGA family to be an ideal package. Applications requiring improved thermal performance and high-speed performance such as desk PCs, laptop PC's, and other similar products benefit from the CPGA attributes.

